

ELECTRICALLY CONDUCTIVE PASTE AND CHIP PARTS

Patent number: JP1315903
Publication date: 1989-12-20
Inventor: OKAMURA AKIO; others: 02
Applicant: TDK CORP
Classification:
- International: H01B1/22; C09D5/24
- European:
Application number: JP19880146520 19880614
Priority number(s):

Abstract of JP1315903

PURPOSE: To enable the formation of an external electrode, etc., of laminated ceramic LC parts with high electrical characteristics and high mechanical strength by containing electrically conductive grains of required shape in a particular ratio.

CONSTITUTION: Spherical electrically conductive grains, having a mean grain size of 0.1-5.0 μ m and a value obtained by division of the mean grain size by a mean thickness smaller than 2, and scaly electrically conductive grains, having a mean grain size of 0.5-20.0 μ m and a value obtained by the division not less than 2, are contained in an electrically conductive paste, containing a solvent and a binder, such that the content of the scaly grains is 40-70 weight% relative to the sum of the both grains. If an external electrode, etc., of a ceramic LC parts are formed and sintered by using this electrically conductive paste with high sintering property, an external electrode with high electrical characteristics and high mechanical strength, capable of having good connection with an internal electrode, and having no possibility of occurrence of cracks and deterioration of impedance or series resistance, can be made.